Application Note No. 021

A Low-Noise-Amplifier shows good Noise Figure performance at 1.9 GHz using BFP405

RF & Protection Devices



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A Low-Noise-Amplifier shows good Noise Figure performance at 1.9 GHz using BFP405 Revision History: 2006-11-08, Rev. 2.0 Previous Version: 2000-07-28						
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Trademarks

 ${\sf SIEGET}^{\tt @} \ {\sf is \ a \ registered \ trademark \ of \ Infineon \ Technologies \ AG.}$

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1 Low-Noise-Amplifier shows good Noise Figure performance at 1.9 GHz using BFP405

This application note describes a low noise amplifier at 1.9 GHz using SIEMENS SIEGET® 25 BFP405. The design emphasis has been on achieving a low noise figure. A circuit description, schematic, PCB layout and components list are shown below together with measured performance data.

Data at 1.9 GHz (3 V and 4.8 mA)

 $\begin{array}{lll} \mbox{Gain:} & \mbox{16 dB} \\ \mbox{IP_{3out}:} & \mbox{8 dBm} \\ \mbox{NF:} & \mbox{1.6 dB} \\ \mbox{$R_{\rm Lin-out}$} & \mbox{>10 dB} \\ \end{array}$

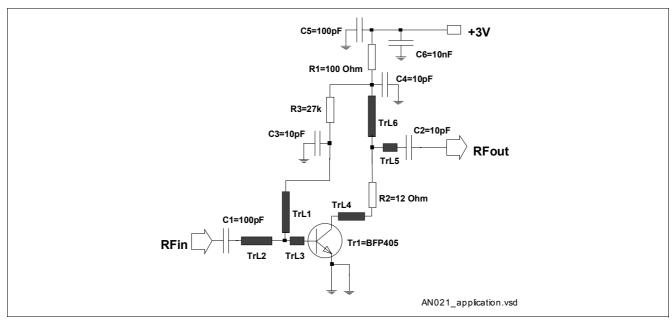


Figure 1 Schematic Diagram

This amplifier at 1.9 GHz has been realized by using microstrip lines as matching elements. The design offers a good compromise between high IIP_3 values, low noise figure and high return loss.

In order to optimize the design for a particular application please observe the following points:

- The layout size can be reduced by using chip-inductors instead of the microstrip lines TrL1 and TrL6
- Improved stabilization behaviour versus temperature and reduced variation in amplifier performance due to the
 device's Beta (current gain) distribution can be achieved by using an active bias circuit. Such a circuit is
 available as a single device from Infineon BCR400W. For further information please refer to Application Note
 No.14. However, the resistors R1 and R3 are sufficient in most applications for stabilization purposes.
- This circuit is not optimized, it is only meant as a first step to a good design. The measured figures include losses of SMA-connectors and the relatively high loss of the microstrip lines on the epoxy-board.
- The use of teflon material would provide an improvement of $\cong 0.1$ dB.
- Resistor R2 is used to improve RF-circuit-stability and return loss values at the output. It also affects the output intermodulation performance.

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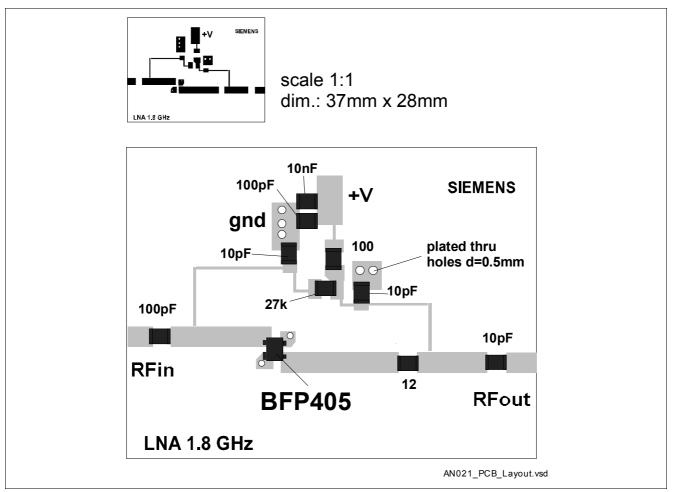


Figure 2 PCB Layout and Component Placement

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Table 1 Component

Component	Value	Unit	Size	Comment
R1	100	Ω	0603	Bias / collector-resistance / $V_{\rm R1} \cong 0.5 \rm V$
R2	10	Ω	0603	To improve stability and output return loss
R3	39	kΩ	0603	Bias / base-resistor
C1	22	pF	0603	Input match
C2	10	pF	0603	Output match
C3	33	pF	0603	RF-short
C4	33	pF	0603	Output match
C5	100	pF	0603	RF-short
C6	10	nF	0603	RF-short
Tr1			SOT343	SIEGET® BFP405
TrL1				Input match, w = 0.3 mm
TrL2				Input match, w = 0.95 mm
TrL3				Input match, w = 0.95 mm
TrL4				Output match, w = 0.95 mm
TrL5				Output match, w = 0.95 mm
TrL6				Output match, w = 0.3 mm
Substrate	FR4			$h = 1 \text{ mm}, \ \epsilon_{\rm r} = 4.5$

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Measurements

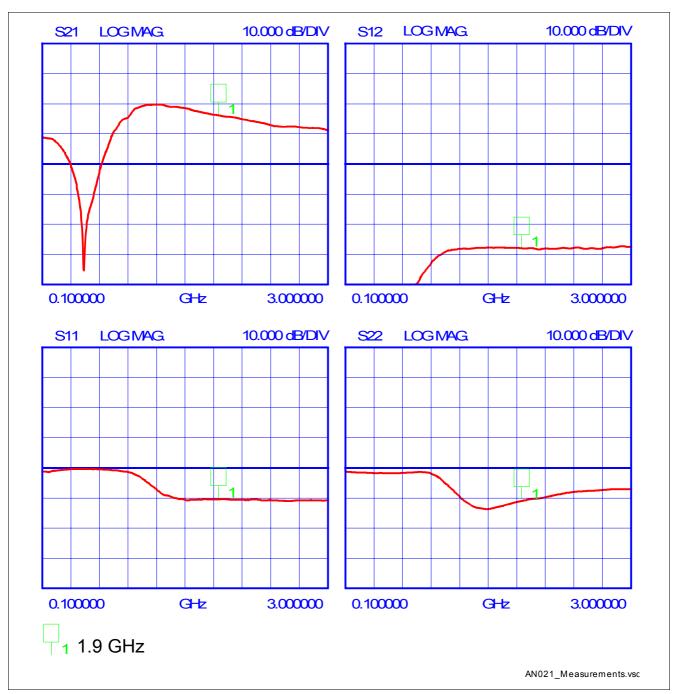


Figure 3 Measurements

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